

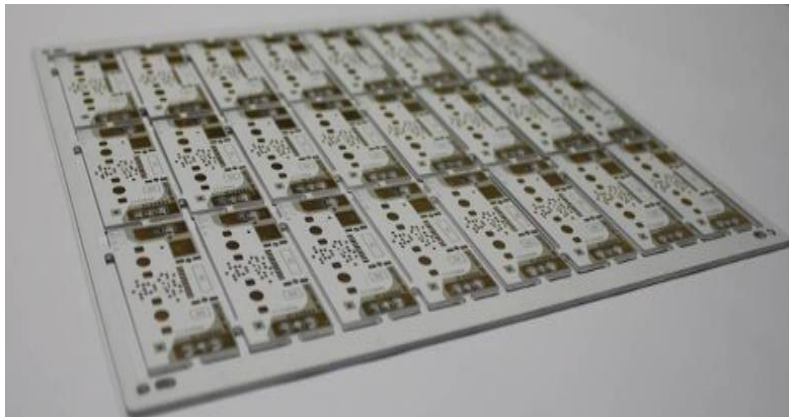
KW-ALS Metal Base Copper Clad Laminate

FEATURES

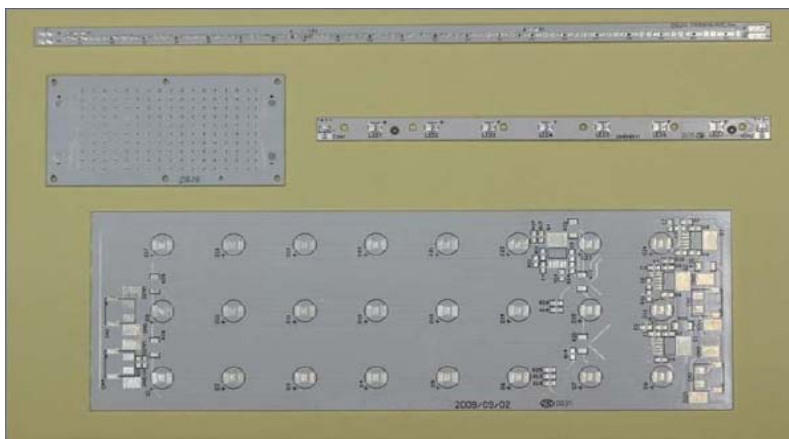
- Excellent heat dissipation
- Excellent thermal and insulation reliability
- Excellent withstand voltage
- Superior processability
- High CTI
- Halogen-Free

APPLICATIONS

- Automotive Electronics
- High Brightness LED
- Power Electronics



Automotive Electronics



Light bar/board for LED lighting

GENERAL PROPERTIES

Item	Test Method	Test Condition	Property Data
Peel Strength(N/mm)	IPC-TM-650	A	>1.2
Flammability	94-V0	A	V-0
Volume resistivity(MΩ·cm)	IPC-TM-650	A	>10 ¹⁰
Surface resistivity(MΩ)	IPC-TM-650	A	>10 ¹⁰
Dielectric constant	IPC-TM-650	1GHz	3.65
Dissipation Factor	IPC-TM-650	1GHz	0.018
Thermal Impedance(m ² ·K/W)	ASTM D5470	A, 246μm	0.000128
Thermal Conductivity(W/(m·K))	ASTM D5470	A, 246μm	2.0
Solder Heat Resistance(sec)	IPC-TM-650	288℃	>360
Breakdown Voltage(KV)	IPC-TM-650	A	>8
Tg(℃)	IPC-TM-650	DSC	>110
Td(℃)	IPC-TM-650	TGA, 5% Loss	>360
Water Content(%)	IPC-TM-650	23℃/24hrs	<0.8
Coefficient of Thermal Expansion(ppm/℃)	IPC-TM-650	<Tg	23.39
		>Tg	53.88
CTI(V)	IEC60112	A	>600

PURCHASING INFORMATION

	Type	Thickness
Copper	E/D Cu	1/2, 1, 2, 4 (oz)
Dielectric Layer	Epoxy resin filled with inorganic filler	80~200 ±20(μm)
Metal Base	Al, Cu, Stainless Steel	0.8, 1.0, 1.2, 1.5, 2.0, 3.0 (mm)
Masking Film	PET/PI Film	\
Standard Size	Max: 630×630 (mm)	